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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural	similarity
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Supplier		User Part Number					
Nexperia B.V.		PMEG3002AELD-Q					
Name of La	aboratory	Part Description					
Assembly reliability labs Based on AEC-Q101 Test		Nexperia DHAM	Schottky				
		MCD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
	TEST						
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113	,				
		Bake Tamb = $125 ^{\circ}\text{C}$	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	208	9760	0	
	5	MIL-STD-750-1					
	HTRB	M1038 Method A					
		Tj = Tjmax, Vr = 100% of max. datasheet					
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0	
	тс	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	53	2400	0	
	, , ,	2					
	UHAST	JESD22-A118					
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %					
		JESD22-A102	— 96 hours	53	2400	0	
	AC	Tamb = $121 ^{\circ}C$, RH = $100 ^{\circ}M$					
# A3 alt	Autoclave	Pressure = $205 \text{ kPa} (29.7 \text{ psia})$					
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of					
# A2 alt		rated reverse voltage ^{[1], [2]}	1000 hours	53	2400	0	
# AZ dit		MIL-STD-750 Method 1037	1000 110015	55	2700	0	
	IOL	ton = toff, devices powered to insure ΔT_i =					
# A5	Intermittent Operating Life		1000 hours	49	2560	0	
π AJ	Internittent Operating Life		1000 110015	77	2000	U	
	RSH	JESD22-A111					
# C8	Resistance to Solder Heat	$260 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$	10 s	n.a.	n 2	n.a.	
# 0	SD	200 C ± J C	10.2	11.d.	n.a.	11. d .	
# C10		J-STD-002		27	1110	0	
# C10	Solderability	des have to be considered (thermal runaway).		37	1110	0	

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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